Case Docket No. ASMJP.100AUS
Date: December 4, 2002

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In re application of:

Kiyoshi Satoh, et al.

App. No.

09/982,454

Filed

October 17, 2001

For

SEMICONDUCTOR

SUBSTRATE-SUPPORTING

**APPARATUS** 

Examiner

A. Crowell

Art Unit

1763

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first class mail in an envelope addressed to: United States Patent and Trademark Office, P.O. Box 2327, Arlington, VA 22202, on

December 4, 2002 (Date)

Katsuhiro Arai, Reg. No. 43,315

UNITED STATES PATENT AND TRADEMARK OFFICE P.O. Box 2327

Arlington, VA 22202

Sir:

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated as shown below:

CLAIMS AS FILED						
	CLAIMS REMAINING AFTER AMENDMENT		HIGHEST NO. PREVIOUSLY PAID FOR	PRESENT EXTRA	RATE	ADDITIONAL FEE
Total Claims	14		20	= 0 ×	\$18	= \$0
Independent Claims	2		3	= 0 ×	\$84	= \$0
Information Disclosu	re Statement filing	g fee				\$180
				TOTAL ADDITIONAL FEE FOR THIS AMENDMENT		\$180

- (X) Amendment in eleven (11) pages
- (X) Information Disclosure Statement; PTO-1449 with three (3) references.
- (X) English translation of the Priority Document.
- (X) A copy of the Response for a Request Substitute Papers filed by the facsimile on October 17, 2001 in thirty (30) pages.
- (X) Return prepaid postcard.
- (X) A check in the amount of \$180.00 is enclosed.

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- (X) Please charge any additional fees, including any fees for additional extension of time, or credit overpayment to Deposit Account No. 11-1410.
- (X) Please use Customer No. 20,995 for the correspondence address.

Katsuhiro Arai Registration No. 43,315 Agent of Record

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IP\_100AUS **PATENT** IN THE UNITED STATES PATENT AND TRADEMARK OFFICE Satoh et al. Group Art Unit 1763 Appl. No. 09/982,454 Filed October 17, 2001 For **SEMICONDUCTOR** SUBSTRATE-SUPPORTING APPARATUS TC 1700 MAIL ROOM Examiner A. Crowell **AMENDMENT** Assistant Commissioner for Patents

Dear Sir:

In response to the Office Action mailed September 5, 2002 (Paper number 6), please amend the above-identified application as follows:

## IN THE CLAIMS:

Washington, D.C. 20231

Please cancel Claims 6, 8, and 17-20.

Please amend Claims 1, 4, 7, 10, and 13 as follows:

1. (Amended) A semiconductor substrate-supporting apparatus for supporting and heating a single semiconductor substrate inside a vacuum-pumped reaction chamber, comprising:

a substrate-supporting surface having a concave portion including a depression slanting toward the center of the substrate-supporting surface, wherein only a peripheral portion of the back surface of the substrate, when loaded, contacts the slanting surface of the concave portion;

a surface peripheral portion formed around the substrate-supporting surface, said surface peripheral portion having a lip portion which protrudes in a ring shape, said lip portion having a top surface and a slanted inner side surface to prevent a plasma from

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